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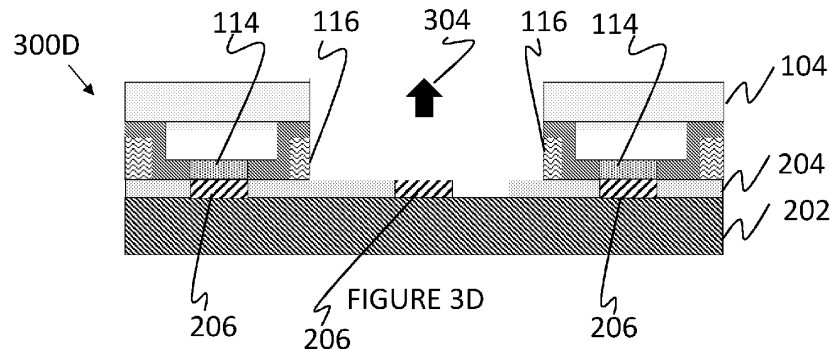
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(54) Title: METHOD OF FORMING A DISPLAY AND DISPLAY



(57) Abstract: A method of forming a display comprising: bonding a backplane comprising a plurality of backplane electrical contacts to a monolithic light emitting diode structure comprising a corresponding plurality of electrical contacts, wherein bonding comprises forming a reversible bond between at least one of the plurality of backplane electrical contacts and a corresponding electrical contact of the monolithic light emitting diode structure; and removing material from the monolithic light emitting diode structure to provide a plurality of physically isolated light emitting diode dies, thereby to enable removal and/or replacement of at least one physically isolated light emitting diode die by reversing the reversible bond between the at least one of the plurality of backplane electrical contacts and the corresponding electrical contact of the monolithic light emitting diode structure.

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